

ATTACHMENT C
Amendments to the Claims

Please cancel claims 1-15 without prejudice or disclaimer.

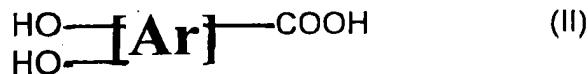
This listing of claims will replace all prior versions, and listings, of claims in the application.

16. (New) A compound that is capable of being hydrogen bonded to form a supramolecular assembly, said compound having the general formula (I):



where:

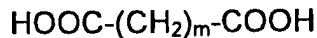
A may be the same or different and A is an aromatic moiety of the general formula (II):



where Ar is an unsubstituted or substituted aromatic nucleus forming a moiety containing at least one hydrogen bond donor and/or acceptor sites,

N may be the same or different and N is a moiety containing at least one hydrogen bond donor and/or acceptor,

X may be the same or different and X is residue of an alkyl diacid of the general formula:



or a functional derivative thereof, wherein m is an integer having a value of at least 2, a difunctional spacer linkage or unit and n is an integer having a value of at least one.

17. (New) The compound of claim 16 wherein Ar is phenyl or benzyl.
18. (New) The compound of claim 16 wherein the compound of Formula (II) is 2,5-dihydroxybenzoic acid or 2,2-dihydroxybenzoic acid.
19. (New) The compound of claim 16 wherein N is a moiety containing at least three hydrogen bond acceptance or donation sites.
20. (New) The compound of claim 16 wherein X is derived from dodecanedioic-, decanedioic-, octanedioic- or hexanedioic acids or an acid chloride thereof.
21. (New) The supramolecular assembly comprising a plurality of hydrogen bonded molecules comprising the aggregation of compounds of the general formula (I) of claim 16.
22. (New) An artefact manufactured from an assembly as claimed in claim 21.
23. (New) A process for the manufacture of the artefact of claim 22 comprising subjecting said assembly to melt extrusion to form self-adherent fibers.